

DATA SHEET

SAA7212

Integrated MPEG AVG decoder

Preliminary specification
Supersedes data of 1998 Sep 07
File under Integrated Circuits, IC02

2001 Mar 28

Integrated MPEG AVG decoder

SAA7212

FEATURES

General features

- Single external Synchronous DRAM organized as $1\text{ M} \times 16$ interfacing at 81 MHz. Due to efficient memory use in MPEG decoding, more than 1 Mbit available for graphics
- Fast 16-bit data + 8-bit address interface with external controller on 27 MHz. Sustained data rate to external SDRAM ≤ 9 Mbytes/s in bursts of 128 bytes
- Dedicated input for audio and video in PES or ES in byte wide. Data input rate: ≤ 9 Mbytes/s in byte mode. Accompanying strobe signals distinguish between audio and video data
- Dedicated compressed data input compatible with the VLSI VES2020/2030 demultiplexers; video is received in byte format and audio serially
- Audio and/or video can also be input via the CPU interface in PES/ES in 8 or 16-bit parallel format up to a peak data rate of 9 Mbytes/s
- Single 27 MHz external clock for time base reference and internal processing. Internal system time base at 90 kHz can be synchronized via CPU port. All required decoding and presentation clocks are generated internally
- Flexible memory allocation under control of the external CPU enables optimized partitioning of memory for different tasks
- Boundary scan testing implemented
- External SDRAM self test
- Supply voltage 3.3 V
- Package QFP160.

CPU related features

- 16 bits data, 8 bits address, or 16 bits multiplexed bus. Motorola 68xxx and Intel x 86 compatible.
- Support fast DMA transfer
- Flexible bidirectional interface to external SDRAM. Minimum sustained rate is 9 Mbytes/s
- Enhanced block mover allows 3 D data move in the external SDRAM. Picture move/Graphic bit maps construction can be done with minimum CPU support.

MPEG2 system features

- Parsing of MPEG2 PES and MPEG1 packet streams
- Double system time clock counters
- Stand-alone or supervised audio/video synchronization
- Processing of errors flagged by channel decoding section
- Support for retrieval of PES header.

MPEG2 video features

- Decoding of MPEG2 video up to main level, main profile
- Output picture format: CCIR-601 4 : 2 : 2 interlaced pictures. Picture format 720×576 at 50 Hz or 720×480 at 60 Hz
- Support of constant and variable bit rates up to 15 Mbits/s
- Stand-alone or CPU controlled mode for decoding/display processes
- Stand-alone mode can be used by applications requiring still pictures manipulations
- Output interface at 8-bit wide, 27 MHz UYVY multiplexed bus
- Horizontal and vertical pan and scan allows the extraction of a window from the coded picture
- Flexible horizontal scaling from 0.5 up to 4 allows easy aspect ratio conversion including support for 2.21 : 1 aspect ratio movies. In case of shrinking an anti-aliasing pre-filter is applied
- Vertical scaling with fixed factors 0.5, 1 or 2. Factor 0.5, realizing picture shrink. Factor 2 can be used for up-conversion of pictures with 288 (240) lines or less.
- Vertical down-scaling with 0.75 factor, realizing letter box conversion
- Horizontal and vertical scaling can be combined to scale pictures to $\frac{1}{4}$ their original size, thus freeing up screen space for graphic applications like electronic program guides
- Non full screen MPEG pictures will be displayed in a box of which position and background colour are adjustable by the external microcontroller
- Nominal video input buffer size for ml@mp 2.7 Mbit
- Video output may be slaved to internally (master) generated or externally (slave) supplied HV synchronization signals. The position of active video is programmable. Display phase is not affected by MPEG timebase changes.

Integrated MPEG AVG decoder

SAA7212

- Video output direct connectable to SAA718x encoder family
- Various trick modes under control of external microcontroller in stand-alone mode:
 - Freeze field/frame on I or P pictures; restart on I picture
 - Freeze field on B pictures; restart on the next I or P picture.
 - Scanning and decoding of I or I + P pictures in a IBP sequence
 - Single step mode
 - Repeat/skip field for time base correction.

MPEG2 audio features

- Decoding of 2 channels, layer I and II MPEG audio. Support for mono, stereo, intensity stereo and dual channel mode.
- Constant and variable bit rates up to 448 kbit/s
- Supported audio sampling frequencies: 48, 44.1, 32, 24, 22.05 and 16 kHz
- CRC error detection
- 3 decoding modes for dual channel streams: decoding of CH1 only, decoding of CH2 only and decoding of both CH1 and CH2
- Storage of last 54 bytes in ancillary data field
- Dynamic Range Control (DRC) at output
- Independent channel volume control and programmable inter channel crosstalk through a baseband audio processing unit
- Muting possibility via external controller. Automatic muting in case of errors or data lack.
- Generation of 'beeps' with programmable tone height, duration and amplitude
- Serial two channel digital audio output with 16, 18, 20 or 22 bits per sample, compatible either to I²S or Japanese formats. Output can be set to high-impedance mode via the external controller.
- Serial SPDIF audio output. Output can be set to high-impedance mode.
- Clock output 256 or 384 × f_s for external DA converter. Output can be set to high-impedance mode.
- Audio FIFO in external SDRAM. Programmable buffer size, at least 64 kbit is available.
- Synchronization modes: PTS controlled, PTS free running, software controlled, buffer controlled
- PTS register can be set via external controller
- Programmable processing delay compensation
- Software controlled stop and restart functions.

Graphics features

- Graphics are presented in boxes independent of video format
- Screen arrangement of boxes is determined by display list mechanism which allows for multiple boxes, background loading, fast switching, scrolling and fading of regions
- Support of 2, 4, 8-bit/pixel in fixed bit maps format or coded in accordance to the DVB variable/run length standard for region based graphics
- Display colours are obtained via colour look up tables. CLUT output is YUVT at 8-bit for each signal component thus enabling 16 M different colours and 6-bit for T which gives 64 mixing levels with video, (T = transparency).
- Bit-map table mechanism to specify a sub set of entries if the CLUT is larger than required by the coded bit pattern. Supported bit-map tables are 16 to 256, 4 to 256 and 4 to 16.
- Graphics boxes may not overlap vertically. If 256 entry CLUT has to be down loaded, a vertical separation of 1 line is mandatory.
- Optimized memory utilization in MPEG video decoding allows for a storage capacity of 1.2 Mbit for graphics bit maps. Flexibility in memory control enables larger capacity in a lot of applications. Moreover variable length/run length encoding makes better use of available memory capacity for graphics bit maps thus making full screen graphics at 8-bit/pixel feasible.
- Fast CPU access (9 Mbytes/s) enables full 1.2 Mbit bit map update within 20 ms
- Internal support for fast block moves in external SDRAM
- Graphics mechanism can be used for signal generation in the vertical blanking interval. Useful for teletext, wide screen signalling, closed caption, etc.
- Support for a single down loadable cursor of 1k pixel with programmable shape. Supported shapes are 8 × 128 pixels, 16 × 64 pixels, 32 × 32 pixels, 64 × 16 pixels and 128 × 8 pixels.
- Cursor colours obtained via 4 entry CLUT with YUVT at 6,4,4 respectively 2 bits. Mixing of cursor with video + graphics in 4 levels.
- Cursor can be moved freely across the screen without overlapping restrictions.

Integrated MPEG AVG decoder

SAA7212

APPLICATIONS

- Tbf.

GENERAL DESCRIPTION

The SAA7212 is an MPEG2 source decoder which combines audio decoding and video decoding. Additionally to these basic MPEG functions it also provides means for enhanced graphics and/or on-screen display (OSD). Due to an optimized architecture for audio and video decoding, maximum capacity in external memory and processing power from the external CPU is available for graphics support.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{DD}	functional supply voltage	3.0	3.3	3.6	V
$I_{DD(tot)}$	total supply current; $V_{DD} = 3.3$ V	–	tbf	–	mA
f_{clk}	device clock frequency	–30 ppm	27.0	+30 ppm	MHz

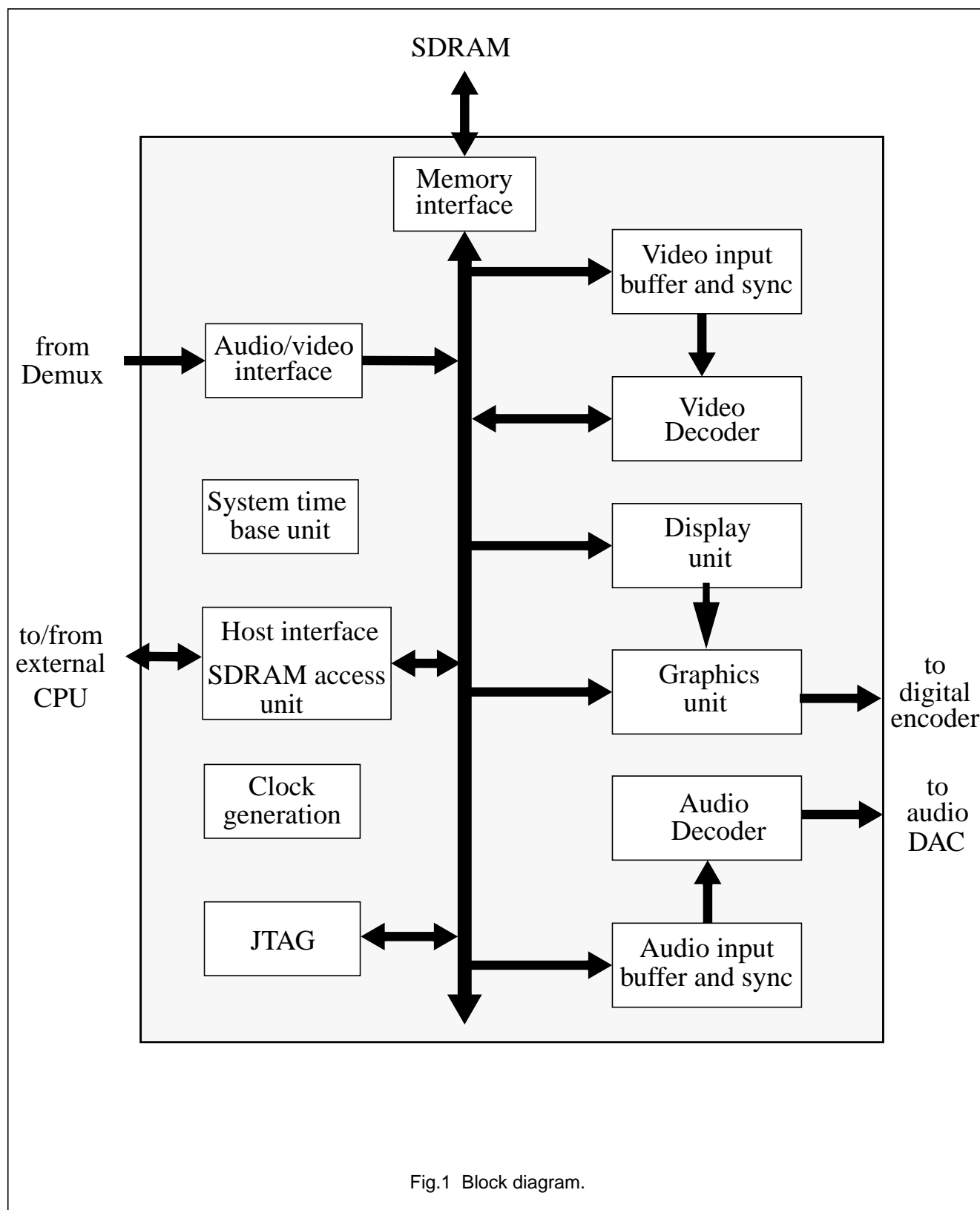
ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
SAA7212H	QFP160	plastic quad flat package; 160 leads (lead length 1.95 mm); body $28 \times 28 \times 3.4$ mm; high stand-off height	SOT322-1

Integrated MPEG AVG decoder

SAA7212

BLOCK DIAGRAM



Integrated MPEG AVG decoder

SAA7212

PINNING

SYMBOL	PIN	DESCRIPTION
MUX	1	multiplexed/non multiplexed bus
CPU_TYPE	2	Intel/Motorola selection
DMA_ACK	3	DMA acknowledge
DMA_REQ	4	DMA request
DMA_DONE	5	DMA end
DMA_RDY	6	DMA ready
V _{SS}	7	ground for pad ring
CS	8	chip select.
DS	9	data strobe
AS	10	address strobe
RWN	11	read/write
DTACK	12	data acknowledge
V _{DD}	13	3.3 V supply for pad ring
IRQ 0	14	individually maskable interrupts
IRQ 1	15	individually maskable interrupts
V_REQ	16	compressed video data request
A_REQ	17	compressed audio data request
V _{SS}	18	ground for pad ring
V _{SSCO}	19	ground for core logic
V _{DDCO}	20	3.3 V supply for core logic
DATA 0	21	CPU data interface
DATA 1	22	CPU data interface
DATA 2	23	CPU data interface
DATA 3	24	CPU data interface
V _{DD}	25	3.3 V supply for pad ring
DATA 4	26	CPU data interface
DATA 5	27	CPU data interface
DATA 6	28	CPU data interface
DATA 7	29	CPU data interface
V _{SS}	30	ground for pad ring
DATA 8	31	CPU data interface
DATA 9	32	CPU data interface
DATA 10	33	CPU data interface
DATA 11	34	CPU data interface
V _{DD}	35	3.3 V supply for pad ring
DATA 12	36	CPU data interface
DATA 13	37	CPU data interface
DATA 14	38	CPU data interface
DATA 15	39	CPU data interface
V _{SS}	40	ground for pad ring

Integrated MPEG AVG decoder

SAA7212

SYMBOL	PIN	DESCRIPTION
ADDRESS 1	41	CPU address interface
ADDRESS 2	42	CPU address interface
ADDRESS 3	43	CPU address interface
ADDRESS 4	44	CPU address interface
V _{DD}	45	3.3 V supply for pad ring
ADDRESS 5	46	CPU address interface
ADDRESS 6	47	CPU address interface
ADDRESS 7	48	CPU address interface
ADDRESS 8	49	CPU address interface
V _{SS}	50	ground for pad ring
V _{SSCO}	51	ground for core logic
V _{DDCO}	52	3.3 V supply for core logic
SDRAM_DATA 0	53	SDRAM data
SDRAM_DATA 15	54	SDRAM data
SDRAM_DATA 1	55	SDRAM data
V _{DD}	56	3.3 V supply for pad ring
SDRAM_DATA 14	57	SDRAM data
SDRAM_DATA 2	58	SDRAM data
SDRAM_DATA 13	59	SDRAM data
V _{SS}	60	ground for pad ring
SDRAM_DATA 3	61	SDRAM data
SDRAM_DATA 12	62	SDRAM data
SDRAM_DATA 4	63	SDRAM data
V _{DD}	64	3.3 V supply for pad ring
SDRAM_DATA 11	65	SDRAM data
SDRAM_DATA 5	66	SDRAM data
SDRAM_DATA 10	67	SDRAM data
V _{SS}	68	ground for pad ring
SDRAM_DATA 6	69	SDRAM data
SDRAM_DATA 9	70	SDRAM data
SDRAM_DATA 7	71	SDRAM data
V _{DD}	72	3.3 V supply for pad ring
SDRAM_DATA 8	73	SDRAM data
SDRAM_WE	74	SDRAM write enable
SDRAM_CAS	75	SDRAM column address strobe
V _{SS}	76	ground for pad ring
SDRAM_RAS	77	SDRAM row address strobe
SDRAM_UDQ	78	SDRAM write mask
V _{DD}	79	3.3 V supply for pad ring
READ_IN	80	read command in
READ_OUT	81	read command out

Integrated MPEG AVG decoder

SAA7212

SYMBOL	PIN	DESCRIPTION
V _{SS}	82	ground for pad ring
CP81MEXT	83	81 MHz SDRAM clock return path
CP81M	84	81 MHz SDRAM memory clock
V _{DD}	85	3.3 V supply for pad ring
SDRAM_ADDR 8	86	SDRAM address
SDRAM_ADDR 9	87	SDRAM address
SDRAM_ADDR 11	88	SDRAM address
V _{SS}	89	ground for pad ring
SDRAM_ADDR 7	90	SDRAM address
SDRAM_ADDR 10	91	SDRAM address
SDRAM_ADDR 6	92	SDRAM address
V _{DD}	93	3.3 V supply for pad ring
SDRAM_ADDR 0	94	SDRAM address
SDRAM_ADDR 5	95	SDRAM address
SDRAM_ADDR 1	96	SDRAM address
V _{SS}	97	ground for pad ring
SDRAM_ADDR 4	98	SDRAM address
SDRAM_ADDR 2	99	SDRAM address
SDRAM_ADDR 3	100	SDRAM address
V _{SSCO}	101	ground for core logic
V _{DDCO}	102	3.3 V supply for core logic
V _{DD}	103	3.3 V supply for pad ring
Test 5	104	IC test interface (see note 2)
Test 6	105	IC test interface (see note 2)
HS	106	horizontal synchronization
VS	107	vertical synchronization
V _{SS}	108	ground for pad ring
YUV 0	109	YUV video output at 27 MHz
YUV 1	110	YUV video output at 27 MHz
YUV 2	111	YUV video output at 27 MHz
YUV 3	112	YUV video output at 27 MHz
V _{DD}	113	3.3 V supply for pad ring
YUV 4	114	YUV video output at 27 MHz
YUV 5	115	YUV video output at 27 MHz
YUV 6	116	YUV video output at 27 MHz
YUV 7	117	YUV video output at 27 MHz
Test 4	118	IC test interface (see note 3)
GRPH	119	indicator for graphics information
Test 3	120	IC test interface (see note 4)
V _{DDAN}	121	3.3 V supply for analog blocks
V _{SSAN}	122	ground for analog blocks

Integrated MPEG AVG decoder

SAA7212

SYMBOL	PIN	DESCRIPTION
V _{SS}	123	ground for pad ring
CLK	124	27 MHz Clock input
V _{SS}	125	ground for pad ring
TCK	126	boundary scan test clock
TRST	127	boundary scan test reset
TMS	128	boundary scan test mode select
TDO	129	boundary scan test data output
TDI	130	boundary scan test data input
V _{DD}	131	3.3 V supply for pad ring
Test 0	132	IC test interface (see note 4)
Test 1	133	IC test interface (see note 4)
Test 2	134	IC test interface (see note 4)
AUDDEN	135	synchronization of the serial audio input (A_DATA)
A_DATA	136	serial audio input
V _{DD}	137	3.3 V supply for pad ring
RESET	138	hard reset input, active LOW
FSCLK	139	256 or 384f _s (audio sampling)
V _{DDCO}	140	3.3 V supply for core logic
V _{SSCO}	141	ground for core logic
SCK	142	serial audio clock
SD	143	serial audio data output
V _{SS}	144	ground for pad ring
WS	145	word select
SPDIF	146	digital audio output
ERROR	147	flag for bitstream error.
V_STROBE	148	video strobe
V _{DD}	149	3.3 V supply for pad ring
AV_DATA 0	150	MPEG stream input port
AV_DATA 1	151	MPEG stream input port
AV_DATA 2	152	MPEG stream input port
AV_DATA 3	153	MPEG stream input port
V _{SS}	154	ground for pad ring
AV_DATA 4	155	MPEG stream input port
AV_DATA 5	156	MPEG stream input port
AV_DATA 6	157	MPEG stream input port
AV_DATA 7	158	MPEG stream input port
A_STROBE	159	audio strobe
V _{DD}	160	3.3 V supply for pad ring

Integrated MPEG AVG decoder

SAA7212

Notes

1. 5 V tolerant outputs swing between V_{SS} and V_{DD} but 5 V tolerant input can receive signal swinging between V_{SS} and 3.3 V or V_{SS} and 5 V.
2. Should be left open in normal mode.
3. Should be tied up to V_{DD} in normal mode.
4. Should be tied down to ground in normal mode.

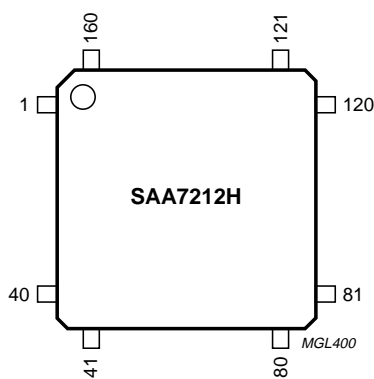


Fig.2 Pin configuration.

Integrated MPEG AVG decoder

SAA7212

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DD}	supply voltage		-0.5	+5	tbF	V
$V_{n(max)}$	voltage on all pins		0	5	tbF	V
P_{tot}	total power dissipation	$T_{amb} = 25\text{ }^{\circ}\text{C}$	–	1	tbF	W
T_{stg}	IC storage temperature		-55	150	tbF	$^{\circ}\text{C}$
T_{amb}	operating ambient temperature		0	70	tbF	$^{\circ}\text{C}$

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient in free air	30	K/W

HANDLING

Inputs and outputs are protected against electrostatic discharges in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling integrated circuits.

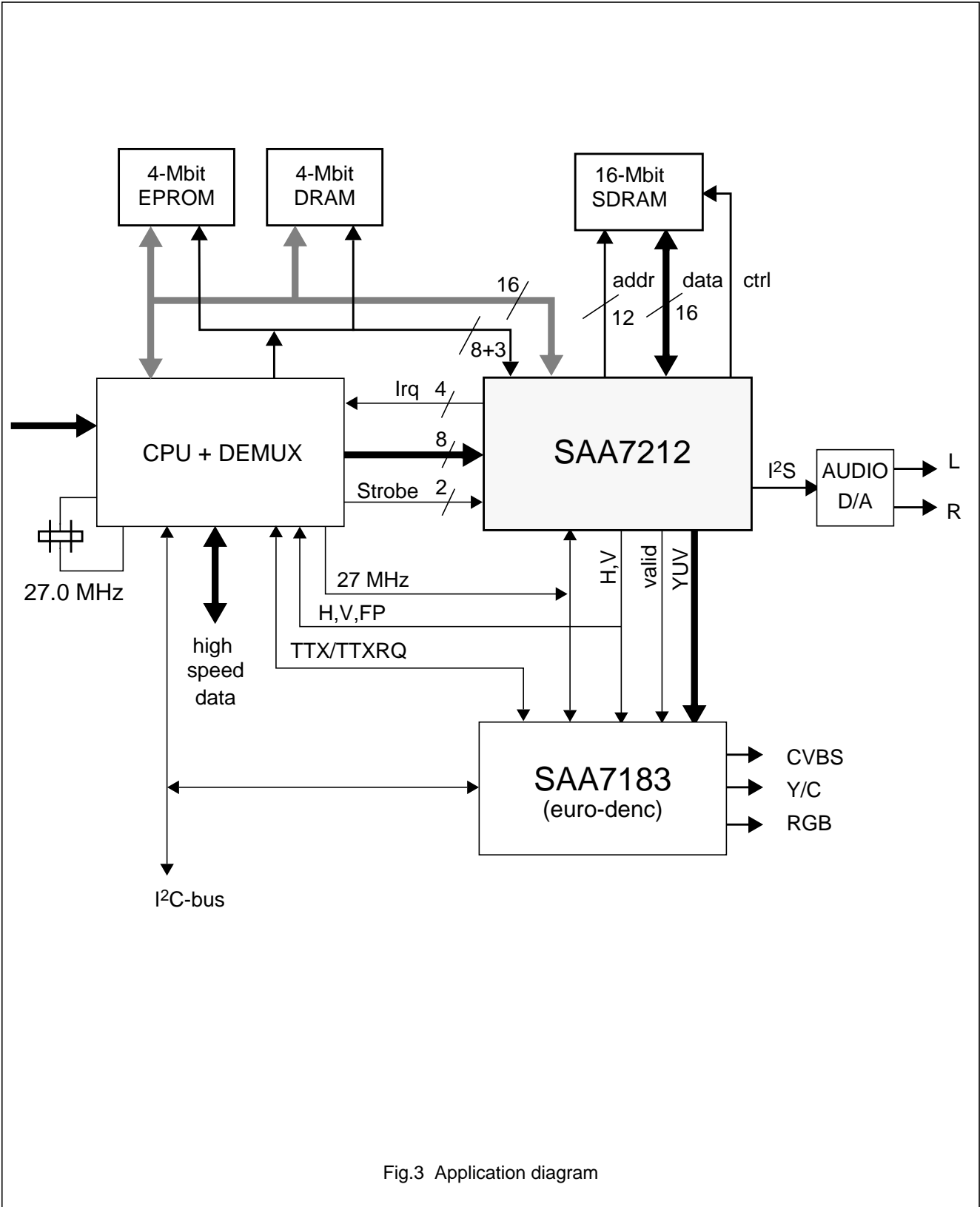
CHARACTERISTICS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
Supply					
V_{DD}	functional supply voltage	3.0	3.3	3.6	V
$I_{DD(tot)}$	total supply current; $V_{DD} = 3.3\text{ V}$	–	tbF	–	mA
Inputs					
$V_{IH(5V\text{ tolerant})}$	input voltage HIGH	2.0	–	6.5	V
V_{IH}	input voltage HIGH	$0.7V_{DD}$	–	$V_{DD}+2.0$	V
$V_{IL(5V\text{ tolerant})}$	input voltage LOW	-0.5	–	0.8	V
V_{IL}	input voltage LOW	-0.5	–	$0.3V_{DD}$	V
I_L	leakage current	–	–	20	μA
C_i	input capacitance	0	–	10	pF
Outputs					
$V_{OH(5V\text{ tolerant})}$	output voltage HIGH	2.4	–	–	V
V_{OH}	output voltage HIGH	$V_{DD} - 0.4$	–	–	V
$V_{OL(5V\text{ tolerant})}$	output voltage LOW	–	–	0.4	V
V_{OL}	output voltage LOW	–	–	0.4	V
DC timing					
T_{cy}	cycle time	–	37.037	–	ns
δ	duty factor	40	–	60	%

Integrated MPEG AVG decoder

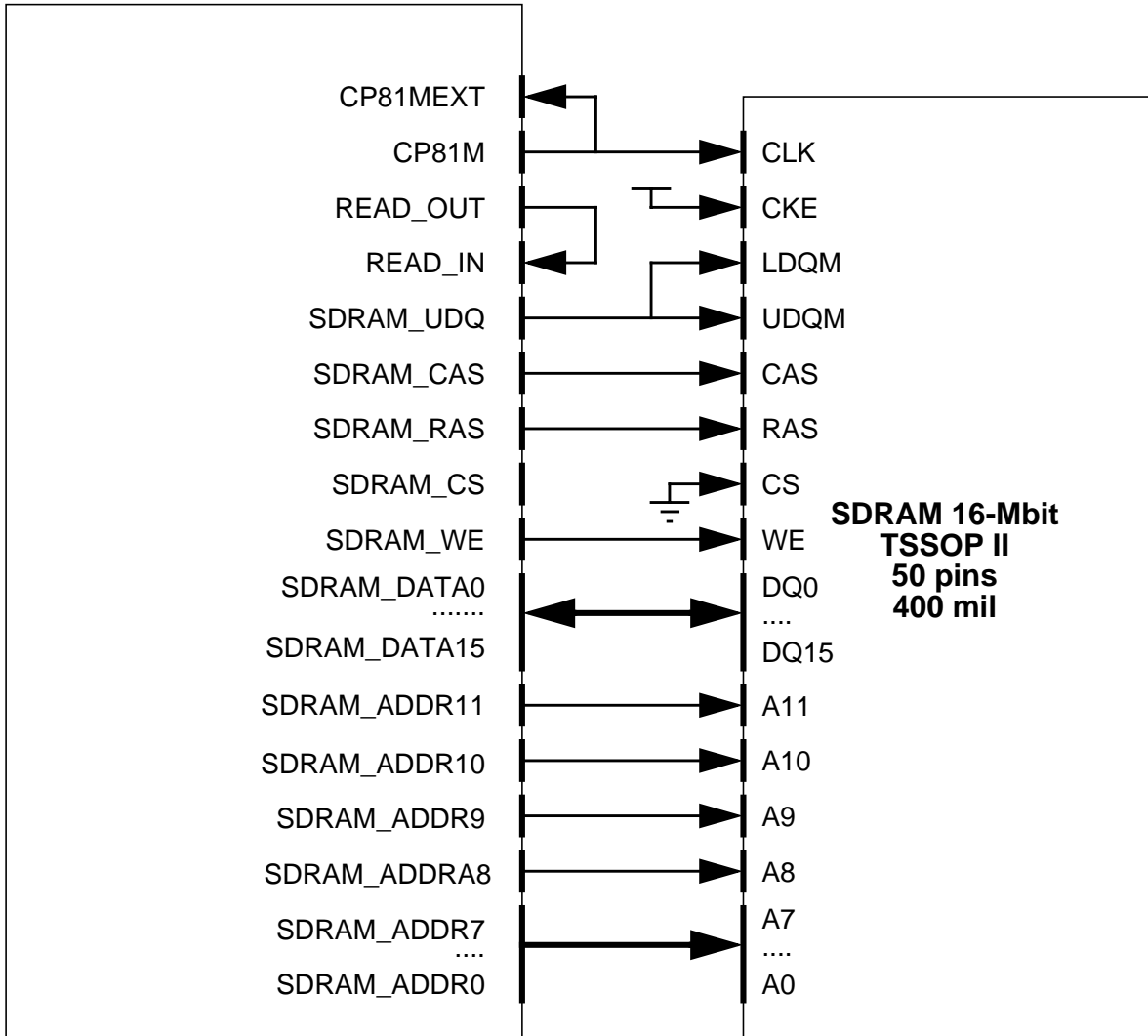
SAA7212

APPLICATION INFORMATION



Integrated MPEG AVG decoder

SAA7212



The board should be designed to insure a similar load on the CP81M and READ_OUT pins as well as a similar fly time between the CP81M and CP81MEXT pins on one side and the READ_OUT and READ_IN pins on the other side.

Fig.4 Connection SAA7212 SDRAM.

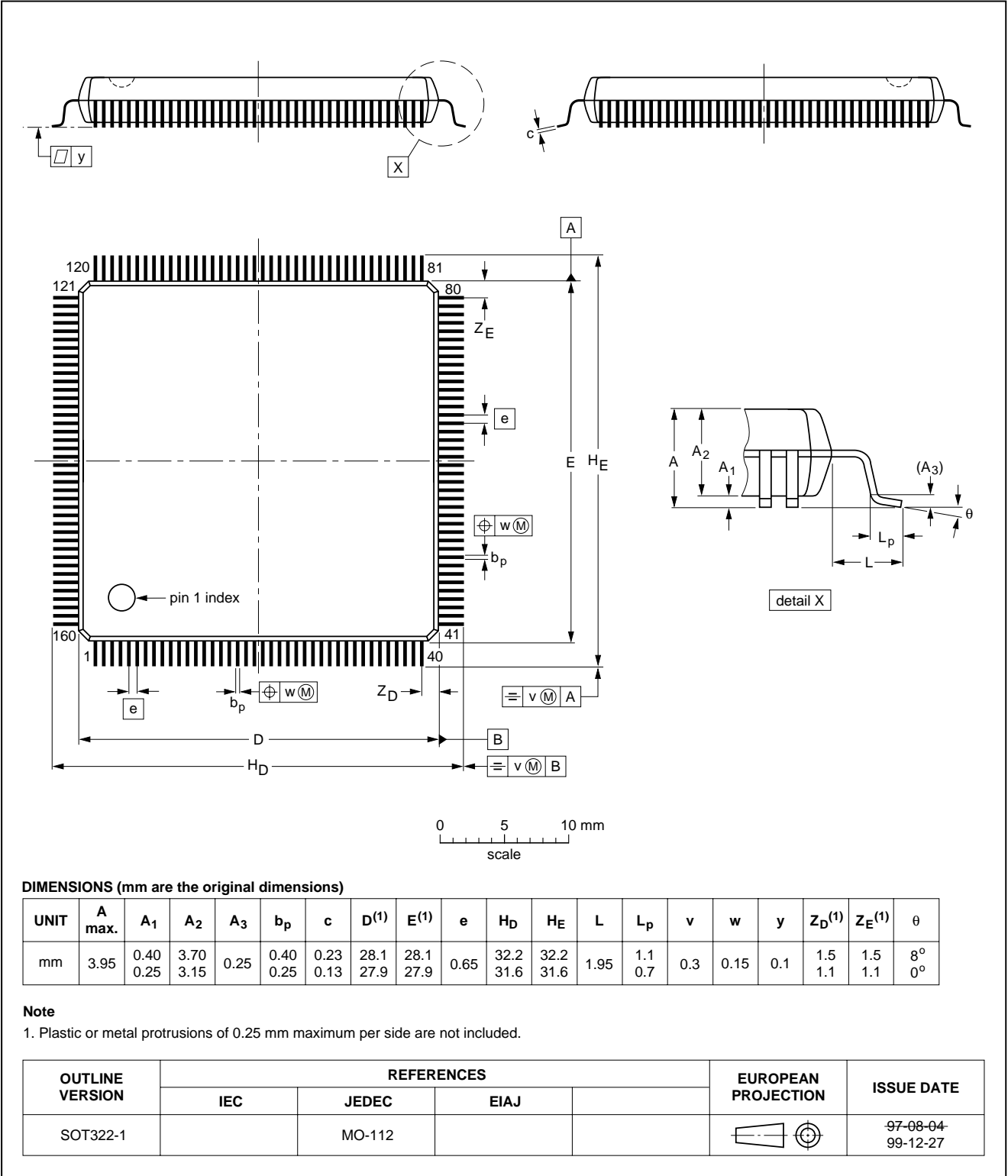
Integrated MPEG AVG decoder

SAA7212

PACKAGE OUTLINE

QFP160: plastic quad flat package;
160 leads (lead length 1.95 mm); body 28 x 28 x 3.4 mm; high stand-off height

SOT322-1



Integrated MPEG AVG decoder

SAA7212

SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

Integrated MPEG AVG decoder

SAA7212

Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE	SOLDERING METHOD	
	WAVE	REFLOW ⁽¹⁾
BGA, HBGA, LFBGA, SQFP, TFBGA	not suitable	suitable
HBCC, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, SMS	not suitable ⁽²⁾	suitable
PLCC ⁽³⁾ , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended ⁽³⁾⁽⁴⁾	suitable
SSOP, TSSOP, VSO	not recommended ⁽⁵⁾	suitable

Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.
2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
3. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

Integrated MPEG AVG decoder

SAA7212

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

Notes

1. Please consult the most recently issued data sheet before initiating or completing a design.
2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

DISCLAIMERS

Life support applications — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no licence or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

ICs with MPEG-2 functionality — Use of this product in any manner that complies with the MPEG-2 Standard is expressly prohibited without a license under applicable patents in the MPEG-2 patent portfolio, which license is available from MPEG LA, L.L.C., 250 Steele Street, Suite 300, Denver, Colorado 80206.

Integrated MPEG AVG decoder

SAA7212

NOTES

Integrated MPEG AVG decoder

SAA7212

NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 3 Figtree Drive, HOMEBUSH, NSW 2140,
Tel. +61 2 9704 8141, Fax. +61 2 9704 8139

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 68 9211, Fax. +359 2 68 9102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Sydhavnsgade 23, 1780 COPENHAGEN V,
Tel. +45 33 29 3333, Fax. +45 33 29 3905

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 9 615 800, Fax. +358 9 6158 0920

France: 7 - 9 Rue du Mont Valérien, BP317, 92156 SURESNES Cedex,
Tel. +33 1 4728 6600, Fax. +33 1 4728 6638

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

Hungary: Philips Hungary Ltd., H-1119 Budapest, Fehervari ut 84/A,
Tel. +36 1 382 1700, Fax. +36 1 382 1800

India: Philips INDIA Ltd, Band Box Building, 2nd floor,
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,
Tel. +91 22 493 8541, Fax. +91 22 493 0966

Indonesia: PT Philips Development Corporation, Semiconductors Division,
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI),
Tel. +39 039 203 6838, Fax +39 039 203 6800

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,
TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Pakistan: see Singapore

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Al.Jerozolimskie 195 B, 02-222 WARSAW,
Tel. +48 22 5710 000, Fax. +48 22 5710 001

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 319762,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 58088 Newville 2114,
Tel. +27 11 471 5401, Fax. +27 11 471 5398

South America: Al. Vicente Pinzon, 173, 6th floor,
04547-130 SÃO PAULO, SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 821 2382

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 93 301 6312, Fax. +34 93 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2741 Fax. +41 1 488 3263

Taiwan: Philips Semiconductors, 5F, No. 96, Chien Kuo N. Rd., Sec. 1,
TAIPEI, Taiwan Tel. +886 2 2134 2451, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
60/14 MOO 11, Bangna Trad Road KM. 3, Bagna, BANGKOK 10260,
Tel. +66 2 361 7910, Fax. +66 2 398 3447

Turkey: Yukari Dudullu, Org. San. Blg., 2.Cad. Nr. 28 81260 Umraniye,
ISTANBUL, Tel. +90 216 522 1500, Fax. +90 216 522 1813

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 3341 299, Fax. +381 11 3342 553

For all other countries apply to: Philips Semiconductors,
Marketing Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN,
The Netherlands, Fax. +31 40 27 24825

Internet: <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 2001

SCA 72

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

753504/03/pp20

Date of release: 2001 Mar 28

Document order number: 9397 750 08178

Let's make things better.

Philips
Semiconductors



PHILIPS